Product / Process Change Notification

N° 2017-059-A

Dear Customer,

Please find attached our INFINEON Technologies PCN:

Introduction of an Additional Wafer Test Location in Kulim, Malaysia Affecting Several Products

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **13. April 2018**.
- Infineon aligns with the widely-recognized JEDEC STANDARD **"JESD46",** which stipulates: **"Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change."**

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG
Postal Address Headquarters: Am Campeon 1-15, D-85579 Neubiberg, Phone +49 (0)89 234-0
Chairman of the Supervisory Board: Dr. Eckart Sünner
Management Board: Dr. Reinhard Ploss (CEO), Dominik Asam, Dr. Helmut Gassel, Jochen Hanebeck
Registered Office: Neubiberg Commercial Register
Amtsgericht München HRB 126492

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▶ Products affected:

Please refer to affected product list 1_cip17059_a

▶ Detailed Change Information:

Subject:

Introduction of an additional wafer test location in Kulim, Malaysia affecting several products

Reason:

Expansion of wafer test capacity.

Due to continuously raising demand for Infineon automotive products we have to implement the well-known front end (FE) Kulim (Malaysia) as an additional wafer test location.

Description:

Old	New
■ Infineon Technologies Austria AG, Villach, Austria	■ Infineon Technologies (Kulim) Sdn. Bhd, Kulim, Malaysia *or* ■ Infineon Technologies Austria AG, Villach, Austria

▶ Product Identification:

Traceability is ensured by lotnumber.

▶ Impact of Change:

No change in form fit or function and no impact on quality and reliability of the final product.
The wafer test location verification is performed via the Advanced Measurement System Analysis (AMSA) methodology.

▶ Attachments:

1_cip17059_a Affected product list

▶ Time Schedule:

■ Final qualification report:	available
■ First samples available:	N.A.
■ Intended start of delivery:	01-September-2018

If you have any questions, please do not hesitate to contact your local Sales office.